

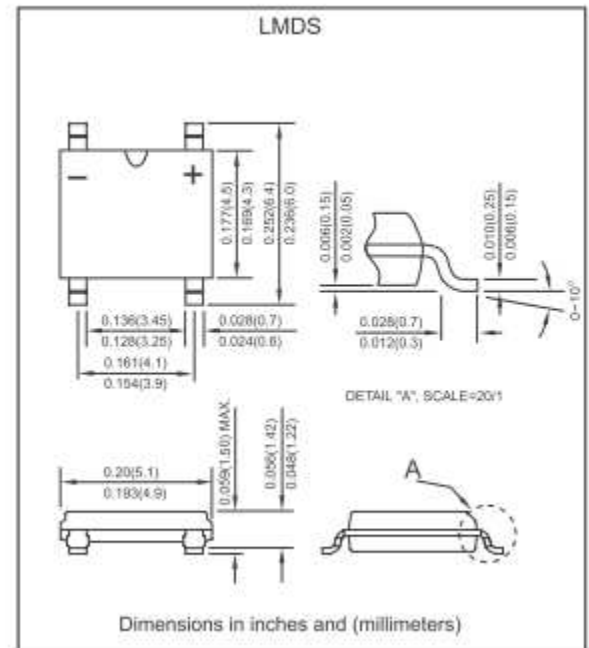
Features

- ◆ Glass passivated junction
- ◆ Ideal for printed circuit board
- ◆ Reliable low cost construction utilizing molded plastic technique
- ◆ High temperature soldering guaranteed:
260°C / 10 seconds / 0.375" (9.5mm)
lead length at 5 lbs., (2.3 kg) tension
- ◆ High surge current capability
- ◆ Suffix "-H" indicates Halogen-free part, ex.ECCBRABS2-6-H.

Mechanical Data

- ◆ Epoxy:UL94-V0 rated flame retardant
- ◆ Case : Molded plastic, LMDS
- ◆ Terminals : Solder plated, solderable per
MIL-STD-202, Method 208
- ◆ Polarity : marked on body
- ◆ Mounting Position : Any
- ◆ Weight : Approximated 0.0992 gram

Package outline



Maximum ratings and Electrical Characteristics (At T_A=25 °C unless otherwise noted)

PARAMETER	SYMBOLS	ABS2-6	ABS4-6	ABS6-6	ABS8-6	ABS10-6	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	200	400	600	800	1000	V
Maximum average forward rectified current On aluminum substrate	I _O	1.0					A
Peak forward surge current 8.3 ms single half sine-wave (JEDEC Method)	I _{FSM}	30					A
Maximum instantaneous forward voltage at I _F =1.0A	V _F	1.1					V
Rating for fusing t _F < 8.3 ms	I ² t	3.7					A ² s
Maximum DC reverse current T _J =25°C At rated DC blocking voltage T _J =125°C	I _R	5.0 500					uA
Typical thermal resistance junction to ambient Typical thermal resistance junction to lead	R _{θJA} R _{θJL}	80 25					°C/W
Operating junction temperature range	T _J	-55 to +150					°C
Storage temperature range	T _{STG}	-55 to +150					°C

Rating and characteristic curves

FIG.1-TYPICAL FORWARD CURRENT
DERATING CURVE

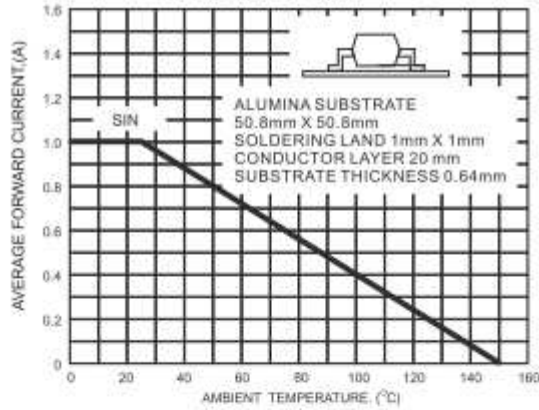


FIG.2-MAXIMUM NON-REPETITIVE FORWARD
SURGE CURRENT

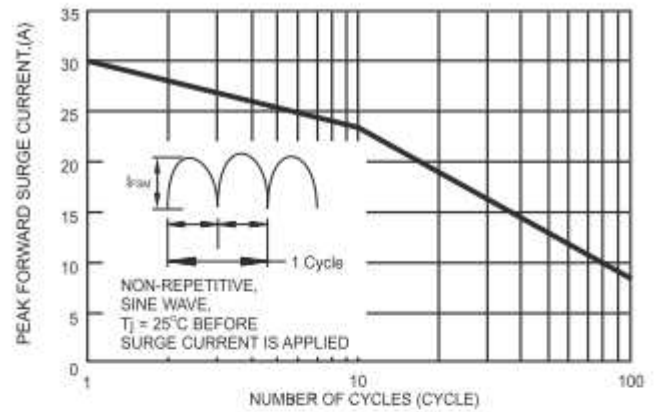


FIG.3-TYPICAL FORWARD
CHARACTERISTICS

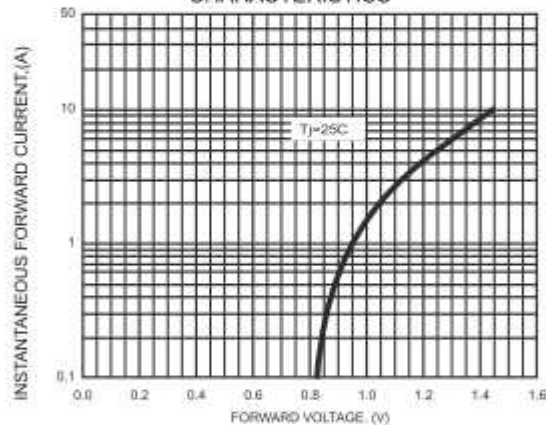


FIG.4-TYPICAL REVERSE
CHARACTERISTICS

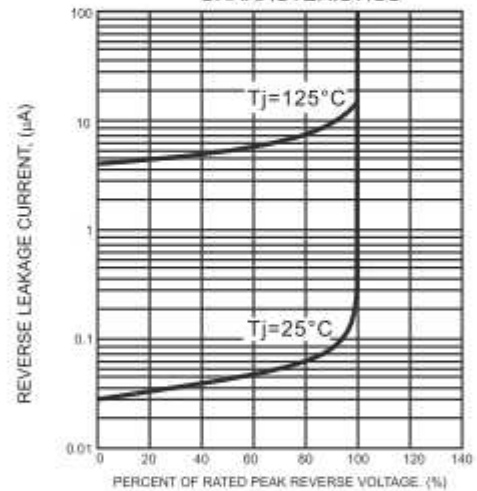
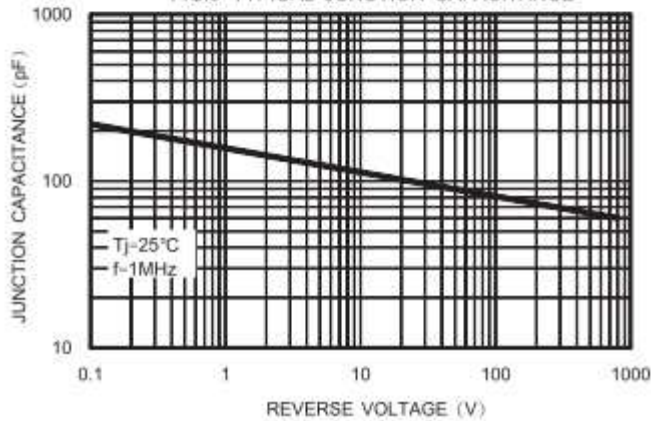
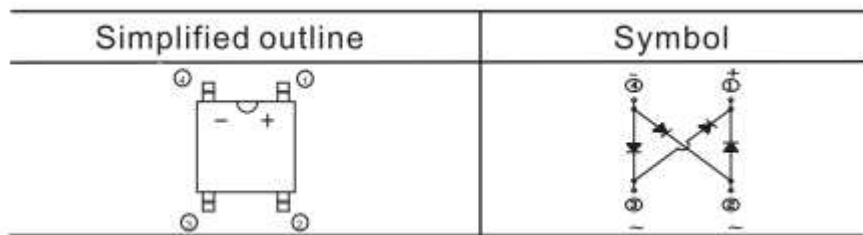


FIG.5-TYPICAL JUNCTION CAPACITANCE



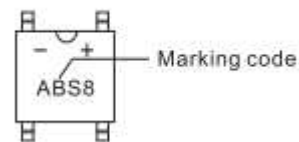
Pinning information



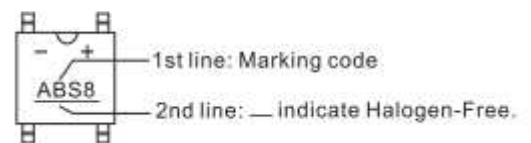
Marking

Part No	Marking
ECCBRABS2-6 / ECCBRABS2-6-H	ABS2
ECCBRABS4-6 / ECCBRABS4-6-H	ABS4
ECCBRABS6-6 / ECCBRABS6-6-H	ABS6
ECCBRABS8-6 / ECCBRABS8-6-H	ABS8
ECCBRABS10-6 / ECCBRABS10-6-H	ABS10

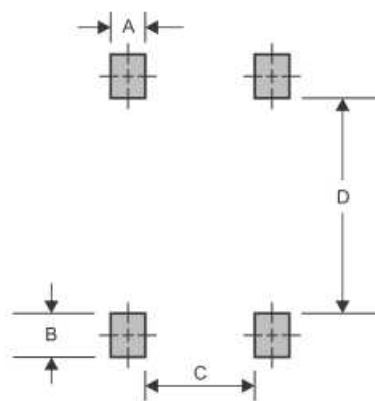
1. For Halogen Device



2. For Halogen-free Device



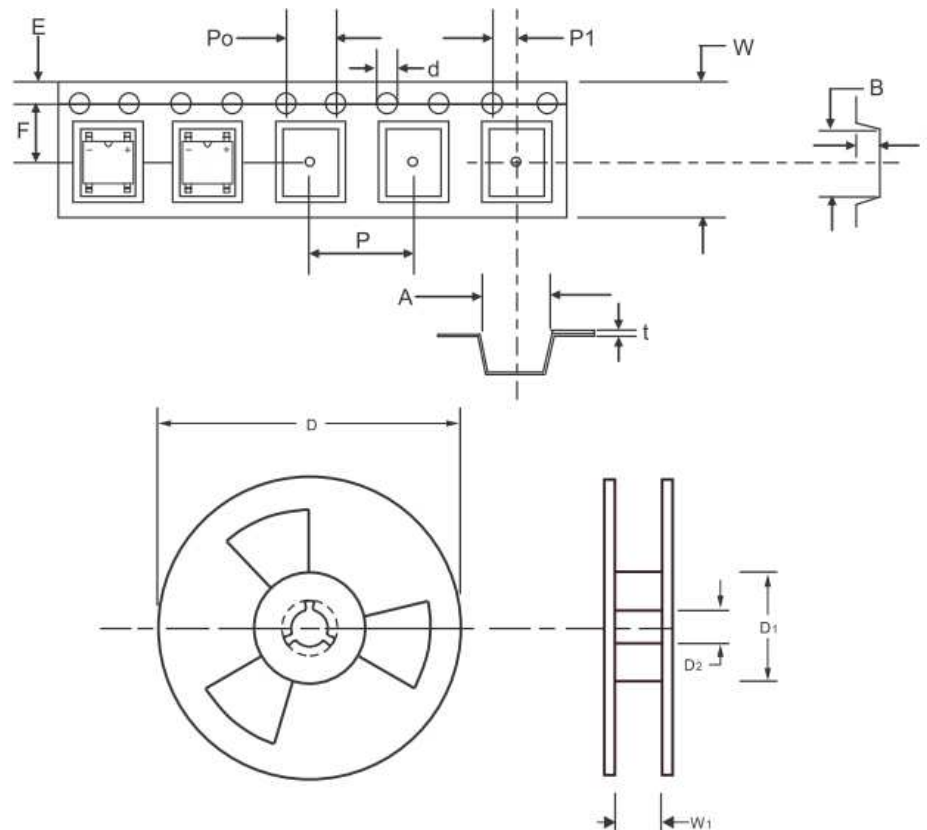
Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C	D
LMDS	0.032 (0.80)	0.032 (0.80)	0.132 (3.35)	0.193 (4.90)

Packing information



unit:mm

Item	Symbol	Tolerance	LMDS
Carrier width	A	0.1	5.31
Carrier length	B	0.1	6.68
Carrier depth	C	0.1	1.60
Sprocket hole	d	0.05	1.55
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
7" Reel outside diameter	D	2.0	-
7" Reel inner diameter	D1	min	-
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.05	5.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.05	2.00
Overall tape thickness	t	0.1	0.30
Tape width	W	0.3	12.00
Reel width	W1	1.0	12~14.4

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
LMDS	13"	5,000	8.0	10,000	337*337*37	330	350*330*360	80,000	19.0